

Title (en)
METHOD FOR THE MANUFACTURE OF AN EXTREMELY THIN FLEXIBLE MULTILAYER PRINTED CIRCUIT BOARD AND A FLEXIBLE MULTILAYER PRINTED CIRCUIT BOARD

Title (de)
VERFAHREN ZUR HERSTELLUNG EINER EXTREM DÜNNEN FLEXIBLEN MEHRSCHICHTIGEN LEITERPLATTE UND FLEXIBLE MEHRSCHICHTIGE LEITERPLATTE

Title (fr)
PROCÉDÉ DE FABRICATION D'UNE CARTE DE CIRCUIT IMPRIMÉ MULTICOUCHE SOUPLE EXTRÊMEMENT MINCE, ET CARTE DE CIRCUIT IMPRIMÉ MULTICOUCHE SOUPLE

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Application
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Abstract (en)
[origin: WO2017134331A1] In the manufacturing method of a multilayer printed circuit board and in a multilayer printed circuit board of the invention, at least part from insulating, conductive or semi-conductive layers remaining inside the multilayer printed circuit board there are manufactured a printed circuit board by using a roll-to-roll manufacturing method for two or several semi-finished printed circuit boards. Between the conductive printed layers of a semi-finished printed circuit board it is possible to manufacture electric vias connecting these by printing. A flexible multilayer printed circuit board is manufactured by connecting at least two semi-finished printed circuit boards face to face so that the pure surfaces of the metal foils of the semi-finished printed circuit boards remain outermost. After this holes can be manufactured through the flexible multilayer printed circuit board, which are metal-plated to produce an electric via.

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Citation (search report)

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- [A] US 2002056192 A1 20020516 - SUWA TOKIHITO [JP], et al
- See references of WO 2017134331A1

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